

Title (en)  
Polishing apparatus

Title (de)  
Poliervorrichtung

Title (fr)  
Appareil de polissage

Publication  
**EP 0860238 A2 19980826 (EN)**

Application  
**EP 98103139 A 19980223**

Priority  
JP 5550497 A 19970224

Abstract (en)  
A polishing apparatus is used for polishing a workpiece such as a semiconductor wafer to a flat mirror finish. The polishing apparatus comprises a turntable having a polishing surface, and a top ring having a pressing surface for holding a workpiece to be polished and pressing the workpiece against the polishing surface of the turntable. At least one of the polishing surface of the turntable and the pressing surface of the top ring is a curved surface such as a convex surface or a concave. <IMAGE>

IPC 1-7  
**B24B 37/04**; **H01L 21/304**

IPC 8 full level  
**B24B 37/11** (2012.01); **B24B 37/12** (2012.01); **B24B 37/16** (2012.01); **B24B 37/30** (2012.01)

CPC (source: EP KR US)  
**B24B 37/11** (2013.01 - EP US); **B24B 37/16** (2013.01 - EP US); **H01L 21/304** (2013.01 - KR)

Cited by  
KR100791728B1; CN107756232A; EP1252974A3; US7040963B1; WO0076723A1

Designated contracting state (EPC)  
DE FR

DOCDB simple family (publication)  
**EP 0860238 A2 19980826**; **EP 0860238 A3 20000517**; **EP 0860238 B1 20030709**; DE 69816146 D1 20030814; DE 69816146 T2 20040527; JP H10235552 A 19980908; KR 100511882 B1 20051031; KR 19980071615 A 19981026; US 5980685 A 19991109; US 6579152 B1 20030617

DOCDB simple family (application)  
**EP 98103139 A 19980223**; DE 69816146 T 19980223; JP 5550497 A 19970224; KR 19980005679 A 19980224; US 2832398 A 19980224; US 42280299 A 19991022